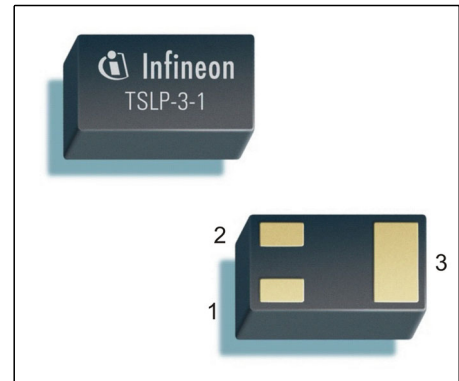


**Linear Low Noise Silicon Bipolar RF Transistor**

- High current capability and low noise figure for wide dynamic range
- Collector design supports supply voltage up to 5V
- Ideal for low phase noise oscillators up to 3.5 GHz
- Low noise figure 1.1 dB at 1.8 GHz
- Pb-free (RoHS compliant) and halogen-free thin small leadless package
- Qualification report according to AEC-Q101 available



**ESD (Electrostatic discharge) sensitive device, observe handling precaution!**

| Type     | Marking | Pin Configuration |       |       | Package  |
|----------|---------|-------------------|-------|-------|----------|
| BFR380L3 | FC      | 1 = B             | 2 = E | 3 = C | TSLP-3-1 |

**Maximum Ratings** at  $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified

| Parameter  | Symbol    | Value       | Unit             |
|--|-----------|-------------|------------------|
| Collector-emitter voltage  | $V_{CEO}$ | 6           | V                |
| Collector-emitter voltage  | $V_{CES}$ | 15          |                  |
| Collector-base voltage   | $V_{CBO}$ | 15          |                  |
| Emitter-base voltage   | $V_{EBO}$ | 2           |                  |
| Collector current  | $I_C$     | 80          | mA               |
| Base current   | $I_B$     | 14          |                  |
| Total power dissipation <sup>1)</sup><br>$T_S \leq 96\text{ }^\circ\text{C}$ | $P_{tot}$ | 380         | mW               |
| Junction temperature   | $T_J$     | 150         | $^\circ\text{C}$ |
| Storage temperature  | $T_{Stg}$ | -55 ... 150 |                  |

**Thermal Resistance**

| Parameter                                | Symbol     | Value | Unit |
|--|------------|-------|------|
| Junction - soldering point <sup>2)</sup> | $R_{thJS}$ | 140   | K/W  |

<sup>1)</sup>  $T_S$  is measured on the collector lead at the soldering point to the pcb

<sup>2)</sup> For the definition of  $R_{thJS}$  please refer to Application Note AN077 (Thermal Resistance Calculation)

**Electrical Characteristics** at  $T_A = 25\text{ °C}$ , unless otherwise specified

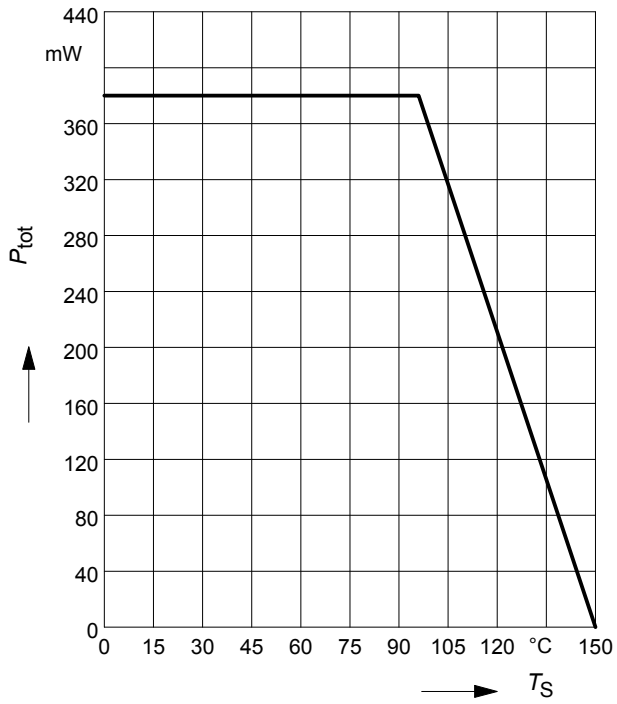
| Parameter   | Symbol        | Values |      |      | Unit |
|---|---------------|--------|------|------|------|
|   |               | min.   | typ. | max. |      |
| <b>DC Characteristics</b>   |               |        |      |      |      |
| Collector-emitter breakdown voltage<br>$I_C = 1\text{ mA}, I_B = 0$   | $V_{(BR)CEO}$ | 6      | 9    | -    | V    |
| Collector-emitter cutoff current<br>$V_{CE} = 5\text{ V}, V_{BE} = 0$<br>$V_{CE} = 15\text{ V}, V_{BE} = 0$ | $I_{CES}$     | -      | 1    | 30   | nA   |
|   |               | -      | -    | 1000 |      |
| Collector-base cutoff current<br>$V_{CB} = 5\text{ V}, I_E = 0$   | $I_{CBO}$     | -      | -    | 30   |      |
| Emitter-base cutoff current<br>$V_{EB} = 1\text{ V}, I_C = 0$   | $I_{EBO}$     | -      | 10   | 500  |      |
| DC current gain<br>$I_C = 40\text{ mA}, V_{CE} = 3\text{ V}$ , pulse measured                               | $h_{FE}$      | 90     | 120  | 160  | -    |

**Electrical Characteristics at  $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified**

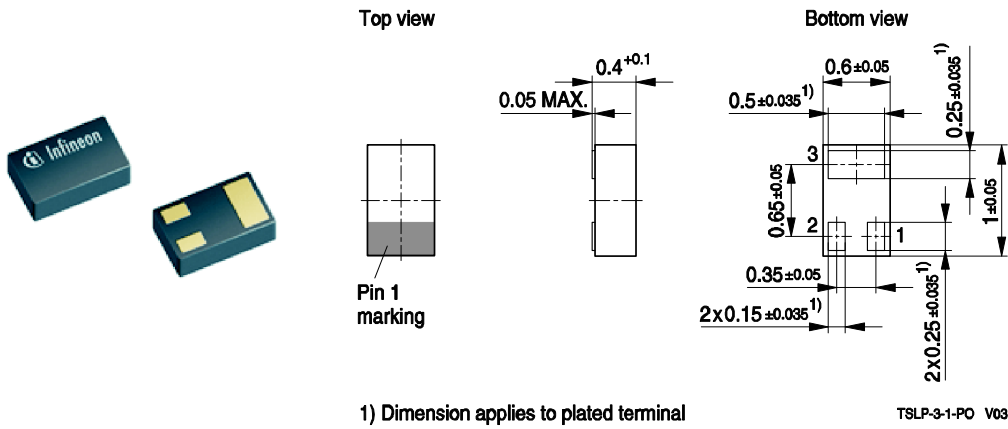
| Parameter   | Symbol        | Values      |             |              | Unit |
|---|---------------|-------------|-------------|--------------|------|
|   |               | min.        | typ.        | max.         |      |
| <b>AC Characteristics (verified by random sampling)</b>   |               |             |             |              |      |
| Transition frequency<br>$I_C = 40\text{ mA}$ , $V_{CE} = 3\text{ V}$ , $f = 1\text{ GHz}$   | $f_T$         | 11          | 14          | -            | GHz  |
| Collector-base capacitance<br>$V_{CB} = 5\text{ V}$ , $f = 1\text{ MHz}$ , $V_{BE} = 0$ ,<br>emitter grounded   | $C_{cb}$      | -           | 0.45        | 0.8          | pF   |
| Collector emitter capacitance<br>$V_{CE} = 5\text{ V}$ , $f = 1\text{ MHz}$ , $V_{BE} = 0$ ,<br>base grounded   | $C_{ce}$      | -           | 0.18        | -            |      |
| Emitter-base capacitance<br>$V_{EB} = 0.5\text{ V}$ , $f = 1\text{ MHz}$ , $V_{CB} = 0$ ,<br>collector grounded   | $C_{eb}$      | -           | 1           | -            |      |
| Minimum noise figure<br>$I_C = 8\text{ mA}$ , $V_{CE} = 3\text{ V}$ , $Z_S = Z_{Sopt}$ ,<br>$f = 1.8\text{ GHz}$  | $NF_{min}$    | 0.5         | 1.1         | 2.1          | dB   |
| Power gain, maximum available <sup>1)</sup><br>$I_C = 40\text{ mA}$ , $V_{CE} = 3\text{ V}$ , $Z_S = Z_{Sopt}$ , $Z_L = Z_{Lopt}$ ,<br>$f = 1.8\text{ GHz}$<br>$f = 3\text{ GHz}$ | $G_{ma}$      | 11.5<br>7.5 | 14<br>10    | 16.5<br>12.5 |      |
| Transducer gain<br>$I_C = 40\text{ mA}$ , $V_{CE} = 3\text{ V}$ , $Z_S = Z_L = 50\Omega$ ,<br>$f = 1.8\text{ GHz}$<br>$f = 3\text{ GHz}$  | $ S_{21e} ^2$ | 9.5<br>5.5  | 11.5<br>7.5 | 13.5<br>9.5  | dB   |
| Third order intercept point at output <sup>2)</sup><br>$V_{CE} = 3\text{ V}$ , $I_C = 40\text{ mA}$ , $f = 1.8\text{ GHz}$ ,<br>$Z_S = Z_L = 50\Omega$                            | $IP3$         | -           | 29.5        | -            | dBm  |
| 1dB compression point at output<br>$I_C = 40\text{ mA}$ , $V_{CE} = 3\text{ V}$ , $f = 1.8\text{ GHz}$<br>$Z_S = Z_L = 50\Omega$<br>$Z_S = Z_{Sopt}$ , $Z_L = Z_{Lopt}$           | $P_{-1dB}$    | -<br>-      | 16<br>19.5  | -<br>-       |      |

<sup>1)</sup> $G_{ma} = |S_{21e}| / |S_{12e}| (k - (k^2 - 1)^{1/2})$ 
<sup>2)</sup>IP3 value depends on termination of all intermodulation frequency components.  
Termination used for this measurement is 50Ω from 0.1 MHz to 6 GHz

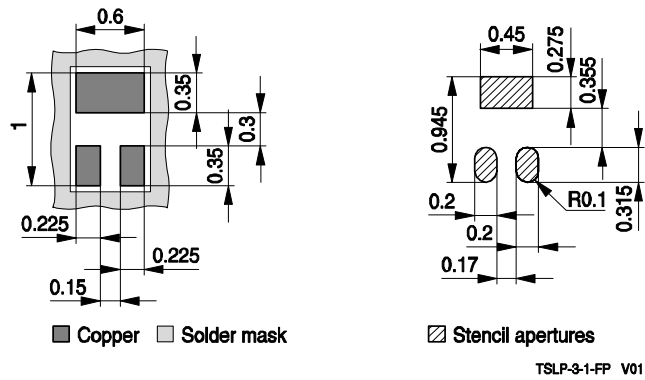
Total power dissipation  $P_{\text{tot}} = f(T_S)$



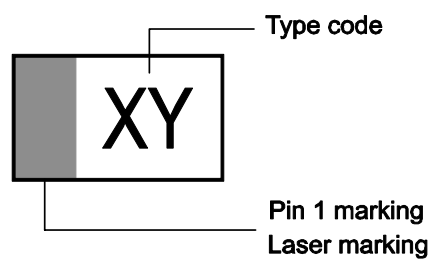
### Package Outline



### Foot Print

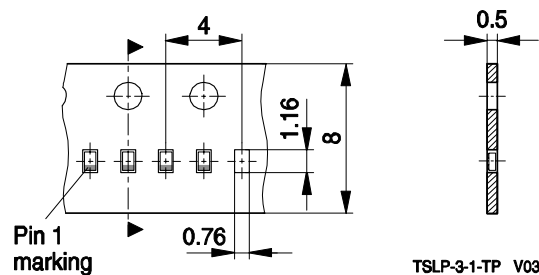


### Marking Layout (Example)



### Standard Packing

Reel Ø 330 mm: 15.000 Pieces/ Reel



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